

Table 2. Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _S	Supply Voltage without Load	30	V
I _O	Output Peak Current (repetitive f >20Hz)	1.7	A
I _O	Output Peak Current (non repetitive, t = 100μs)	2	A
P _{tot}	Total Power Dissipation (T _{case} = 70°C)	8	W
T _{op}	Operating Temperature Range	0 to 70	°C
T _{stg} , T _j	Storage & Junction Temperature	-40 to 150	°C

Figure 3. Pin Connection (Top view)

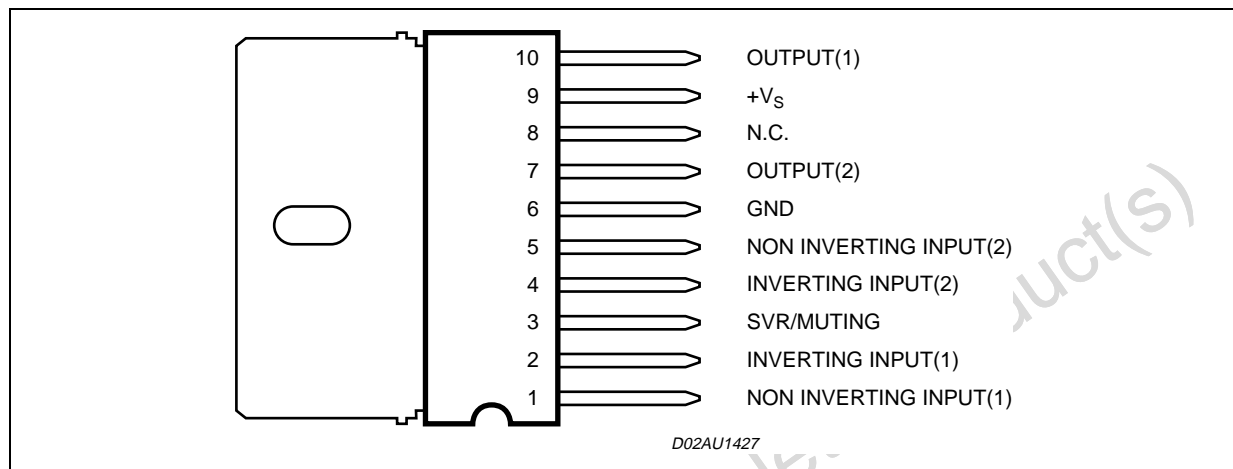


Figure 4. Block Diagram

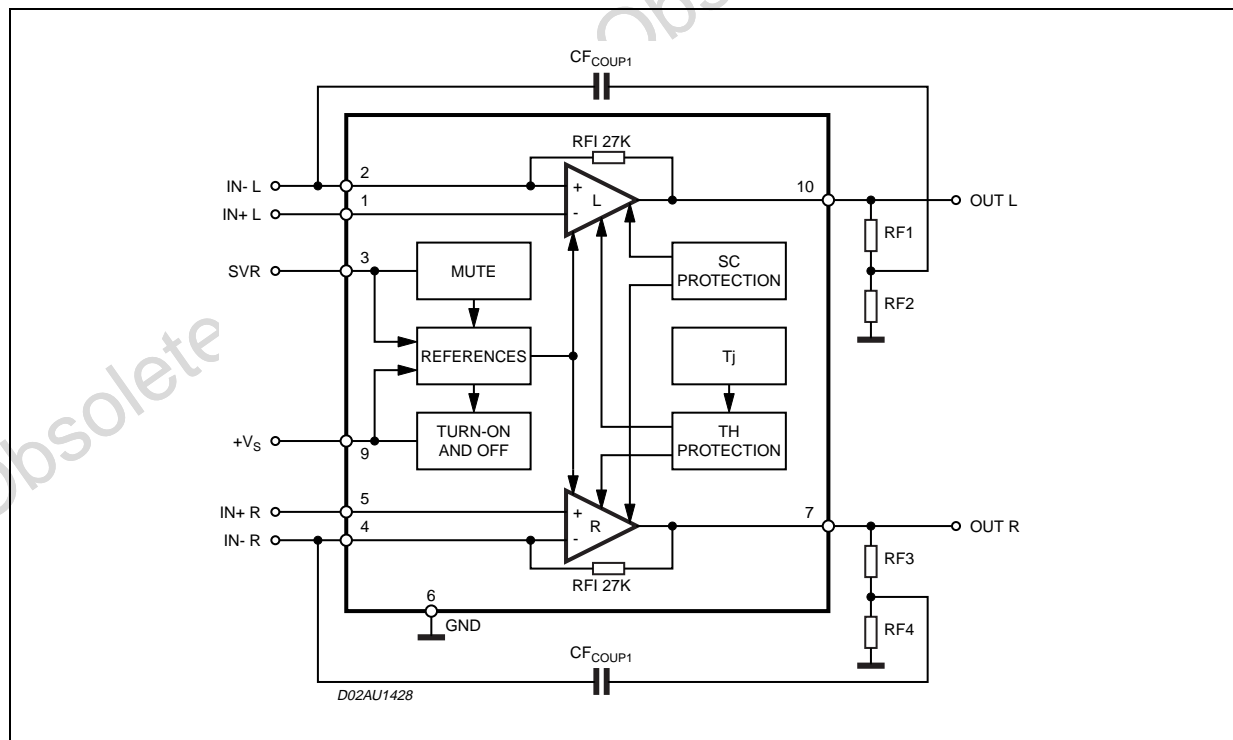


Table 3. Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction to case	Max 9	°C/W

Table 4. ELECTRICAL CHARACTERISTICS

(Refer to the stereo test and application circuit, $V_S = 20V$; $R_L = 8\Omega$; $G_v = 30dB$; $f = 1KHz$; $T_{amb} = 25^\circ C$ unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V_S	Supply Voltage		10		24	V
V_O	Quiescent Output Voltage			9.5		V
I_q	Total Quiescent Current			70	95	mA
P_O	Output Power (RMS)	$d = 10\%$; $T_{amb} = 85^\circ C$	5	6		W
		$d = 1\%$	4	5		W
d	Total Harmonic Distortion	$P_O = 1W$, $f = 1kHz$		0.03	0.3	%
		$f = 100Hz$ to $10KHz$; $P_O = 0.1$ to $3W$			0.5	
C_T	Cross Talk	$R_S = 10K\Omega$; $f = 1KHz$		70		dB
		$R_S = 10K\Omega$; $f = 10KHz$		60		dB
R_I	Input Resistance		100	200		$K\Omega$
f_L	Low Frequency Roll-off (-3dB)			40		Hz
f_H	High Frequency Roll-off (-3dB)			80		KHz
e_N	Total Input Noise Voltage	A Curve; $R_S = 10K\Omega$		1.5		mV
		$f = 22Hz$ to $22KHz$; $R_S = 10K\Omega$		3	10	V
SVR	Supply Voltage Rejection (each channel)	$R_S = 10K\Omega$; $f = 100Hz$; $V_r = 0.5V$	45	60		dB
T_j	Thermal Shutdown Junction Temperature			145		°C
MUTE FUNCTION						
$V_{T_{MUTE}}$	Mute Threshold		1	1.6		V
$V_{T_{PLAY}}$	Play Threshold			4.5		V
ATT_{AM}	Mute Attenuation		70	100		dB
$I_{q_{MUTE}}$	Quiescent Current @ Mute			7	10	mA

3 TYPICAL CHARACTERISTICS

(referred to the typical Application Circuit, $V_S = 20V$, $R_L = 8\Omega$, unless otherwise specified)

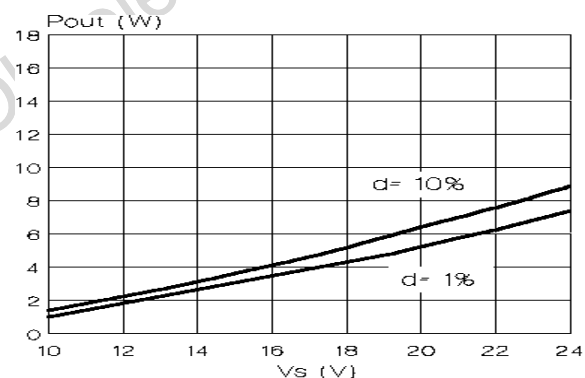
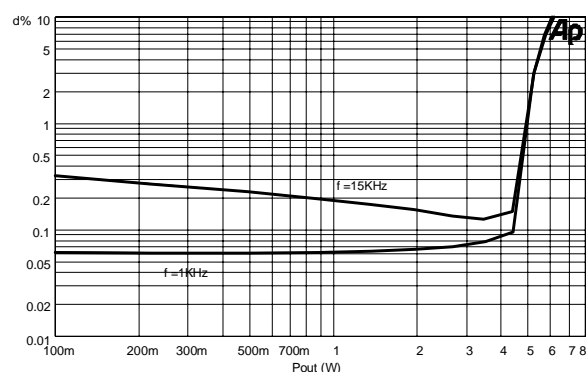
Figure 5. Output Power vs. Supply Voltage**Figure 6. Distortion vs. Output Power**

Figure 7. Quiescent Current vs. Supply Voltage

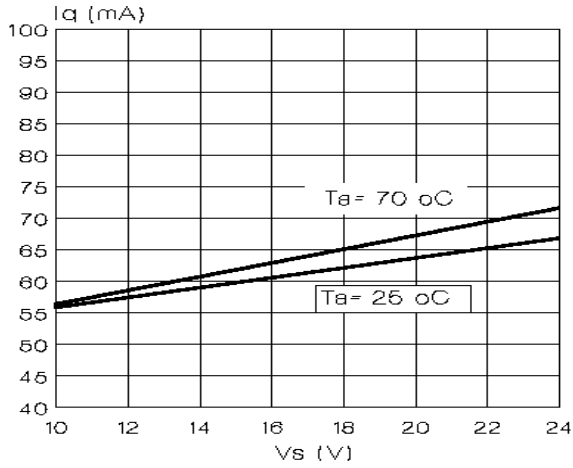


Figure 10. Output Attenuation & Quiescent Current vs. Vpin3

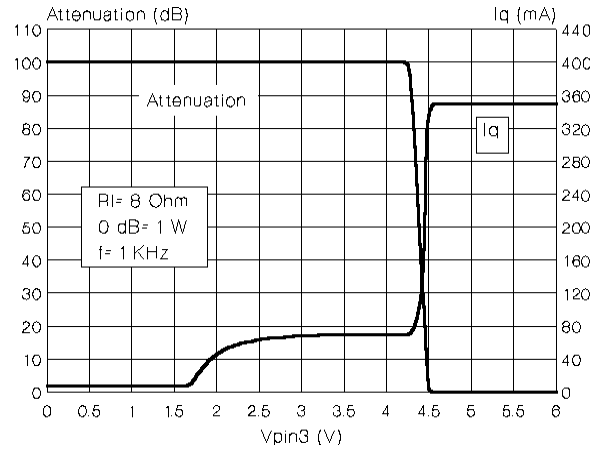


Figure 8. Supply Voltage Rejection vs. Freq.

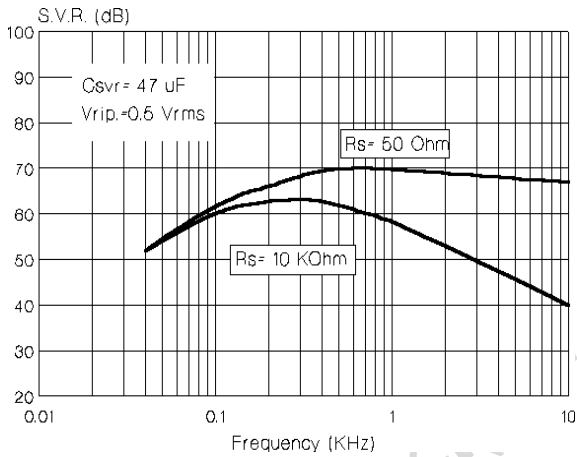


Figure 11. Total Power Dissipation vs. Output Power

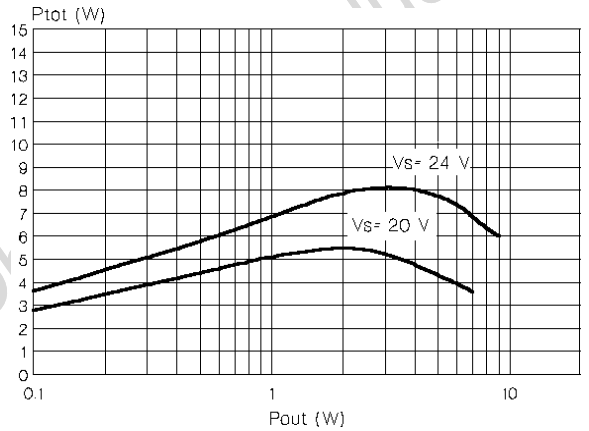


Figure 9. Crosstalk vs. Frequency

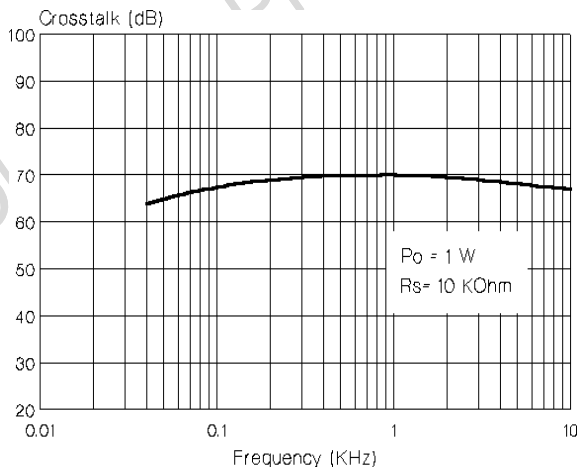


Figure 12. PC Board Component Layout

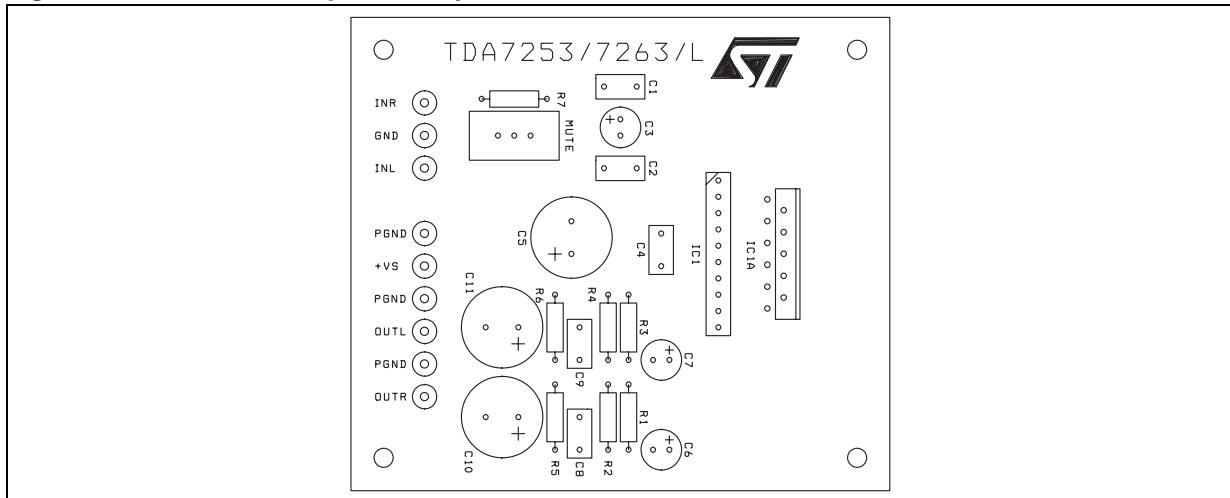


Figure 13. Evaluation Board Top Layer Layout

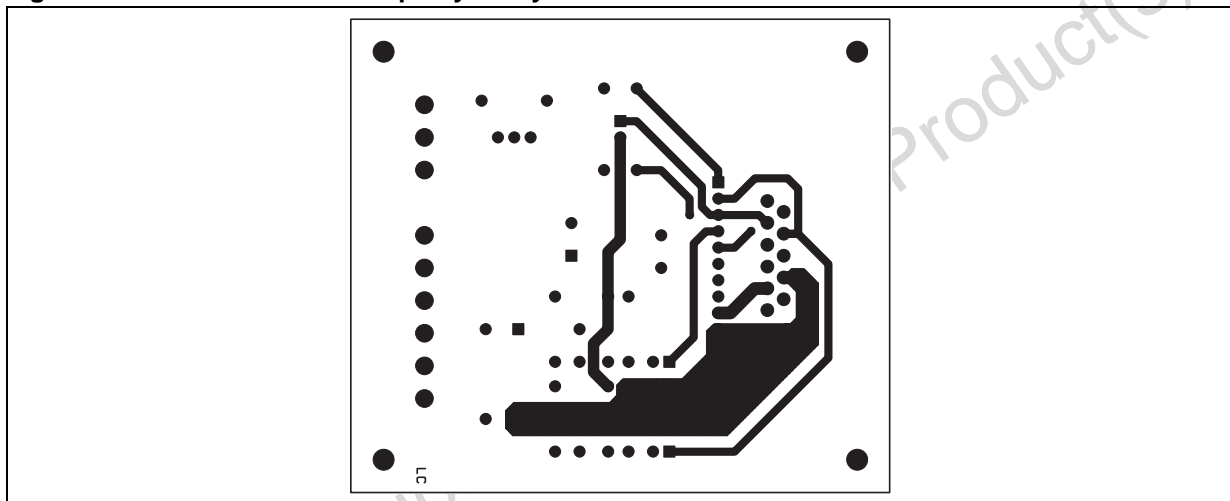
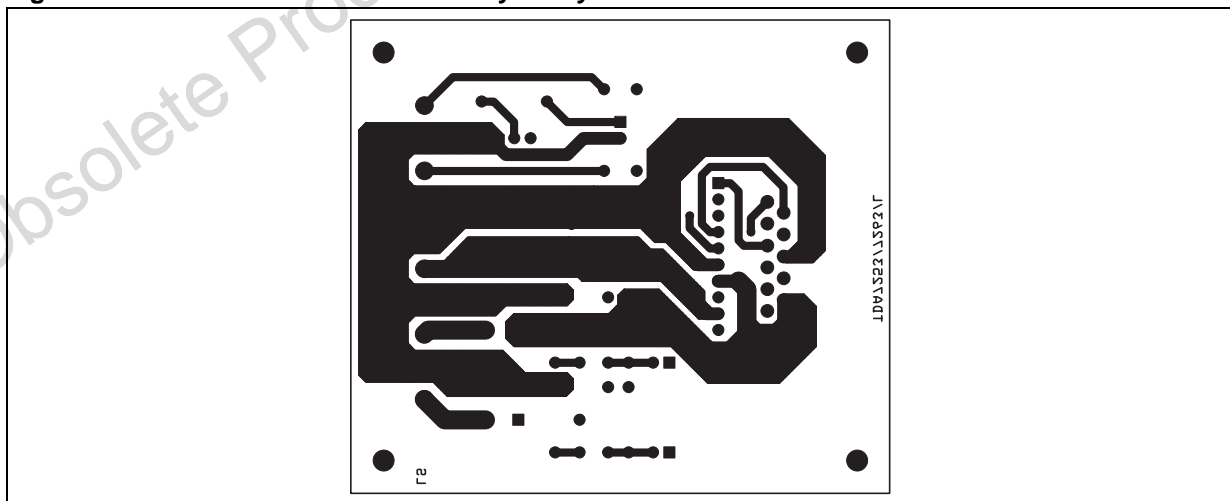


Figure 14. Evaluation Board Bottom Layer Layout



4 APPLICATION SUGGESTION

The recommended values of the components are those shown on the typical application circuit. Different values can be used; the following table can help the designer.

Component	Recomm. Value	Purpose	Larger Than	Smaller Than
R1 and R3	1.5K Ω	Close loop gain setting (*)	Increase of gain	Decrease of gain
R2 and R4	47 Ω	Close loop gain setting (*)	Decrease of gain	Increase of gain
R5 and R6	4.7 Ω	Frequency stability	Danger of oscillations	
C1 and C2	100nF	Input DC decoupling	Higher SVR	Higher low frequency cutoff
C3	47 μ F	- Ripple Rejection - Mute time constant	Increase of the Switch-on time	- Degradation of SVR - Worse turn-off pop by muting
C4	100nF	Supply Voltage Bypass		Danger of oscillations
C5	1000 μ F	Supply Voltage Bypass		
C6 and C7	47 μ F	Feedback input DC decoupling	Increase of the Switch-on time	Danger of Switch-on time
C8 and C9	0.1 μ F	Frequency stability		Danger of oscillations
C10 and C11	1000 μ F	Output DC decoupling		Higher low-frequency cut-off

(*) Closed loop gain must be higher than 26dB

5 BUILT-IN PROTECTION SYSTEMS

5.1 Thermal Shut-down

The presence of a thermal limiting circuit offers the following advantages:

- 1 an overload on the output (even if it is permanent), or an excessive ambient temperature can be easily withstood.
- 2 the heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no device damage in the case of excessive junction temperature; if for any reason the junction temperature increases up to 145°C. the thermal shutdown simply reduces the output power and therefore the power dissipation.

The maximum allowable power dissipation depends upon the thermal resistance junction-ambient. Figure 15 shows the dissipable power as a function of ambient temperature for different heatsink thermal resistance.

5.2 Short Circuit (AC Conditions)

The TDA7263L can withstand accidental short circuits across the speaker made by a wrong connection during normal play operation.

6 HEAT SINK DIMENSIONING:

In order to avoid the thermal protection intervention, that is placed approximatively at $T_j = 150^\circ\text{C}$, it is important the dimensioning of the Heat Sink R_{Th} ($^\circ\text{C}/\text{W}$).

The parameters that influence the dimensioning are:

- Maximum dissipated power for the device (P_{dmax})
- Max thermal resistance Junction to case ($R_{Th\ j-c}$)
- Max. ambient temperature $T_{amb\ max}$
- Quiescent current I_q (mA)

6.1 Example:

$V_{CC} = 20\text{V}$, $R_{load} = 80\text{ohm}$, $R_{Th\ j-c} = 9\ ^\circ\text{C}/\text{W}$, $T_{amb\ max} = 50^\circ\text{C}$

$$P_{dmax} = (N^\circ \text{ channels}) \cdot \frac{2V_{CC}^2}{\Pi^2 \cdot R_{load}} + I_q \cdot V_{CC}$$

$$P_{dmax} = 2 \cdot (2.5) + 0.5 = 5.5\text{W}$$

$$(\text{Heat Sink}) R_{Th\ c-a} = \frac{150 - T_{amb\ max}}{P_{d\ max}} - R_{Th\ j-c} = \frac{150 - 50}{5.5} - 9 = 9.0^\circ\text{C}/\text{W}$$

In figure 11 is shown the Power derating curve for the device.

Figure 15. Power Derating Curve

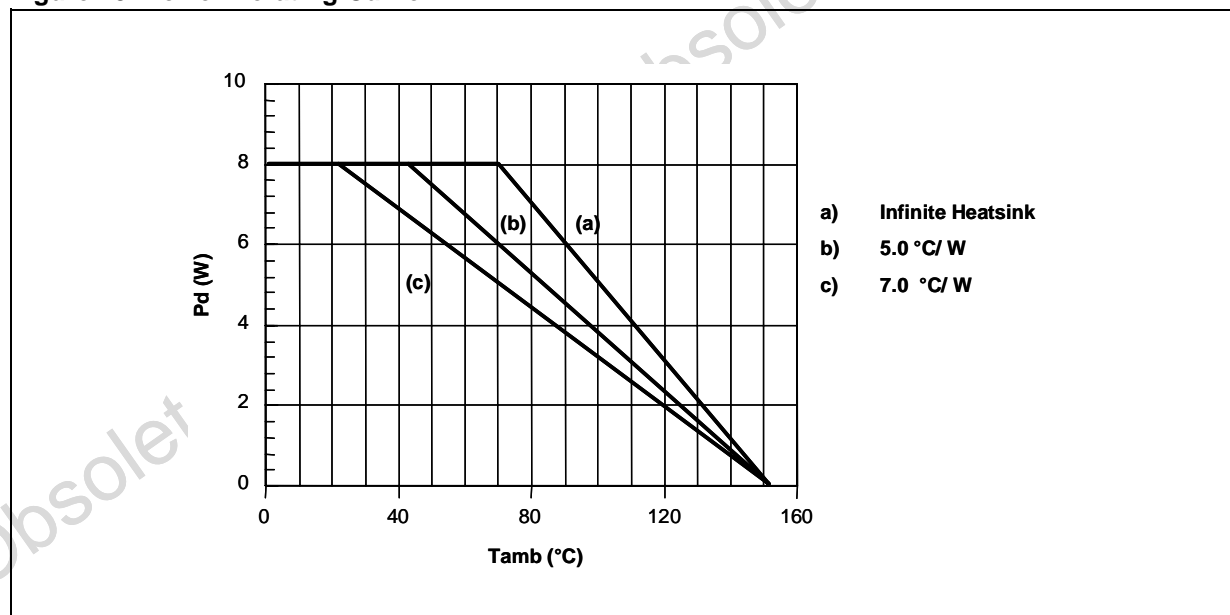
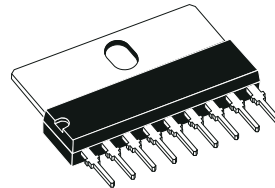


Figure 16. SIP10 Mechanical Data & Package Dimensions

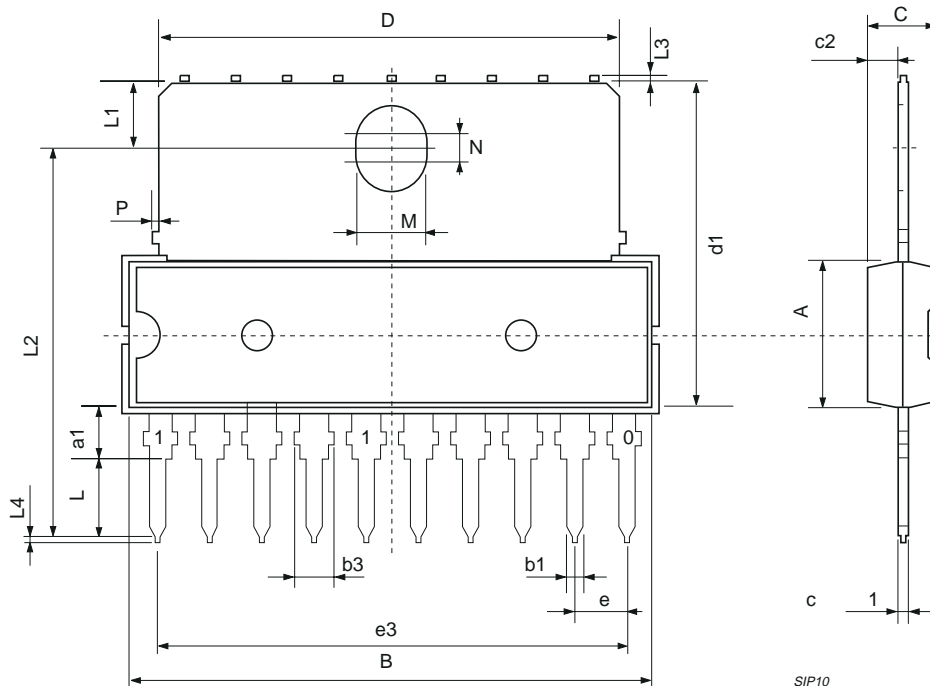
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			7.1			0.280
a1	2.7		3	0.106		0.118
B			24.8			0.976
b1		0.5			0.020	
b3	0.85		1.6	0.033		0.063
C		3.3			0.130	
c1		0.43			0.017	
c2		1.32			0.052	
D			23.7			0.933
d1		14.5			0.571	
e		2.54			0.100	
e3		22.86			0.900	
L	3.1			0.122		
L1		3			0.118	
L2		17.6			0.693	
L3			0.25			0.010
L4			0.254			0.010
M		3.2			0.126	
N		1			0.039	
P			0.15			0.006

OUTLINE AND MECHANICAL DATA

Weight: 2.02gr



SIP10



SIP10

0016108 D

Table 5. Revision History

Date	Revision	Description of Changes
June 2003	1	First Issue
September 2004	2	Changed Status and the graphic aspect in compliant to the new rules "Corporate Technical Publications Design Guide"

Obsolete Product(s) - Obsolete Product(s)

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